

# **EEE-2103: Electronic Devices and Circuits**

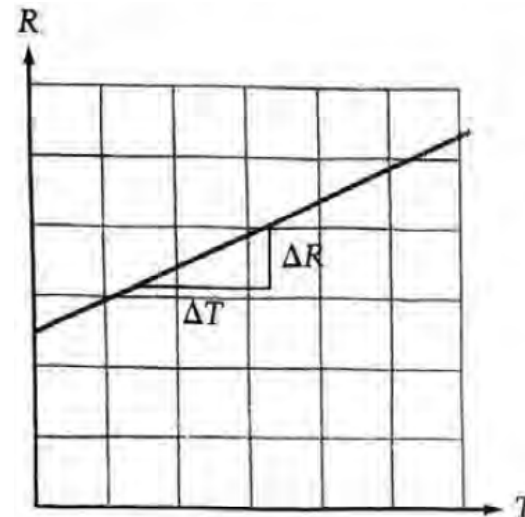
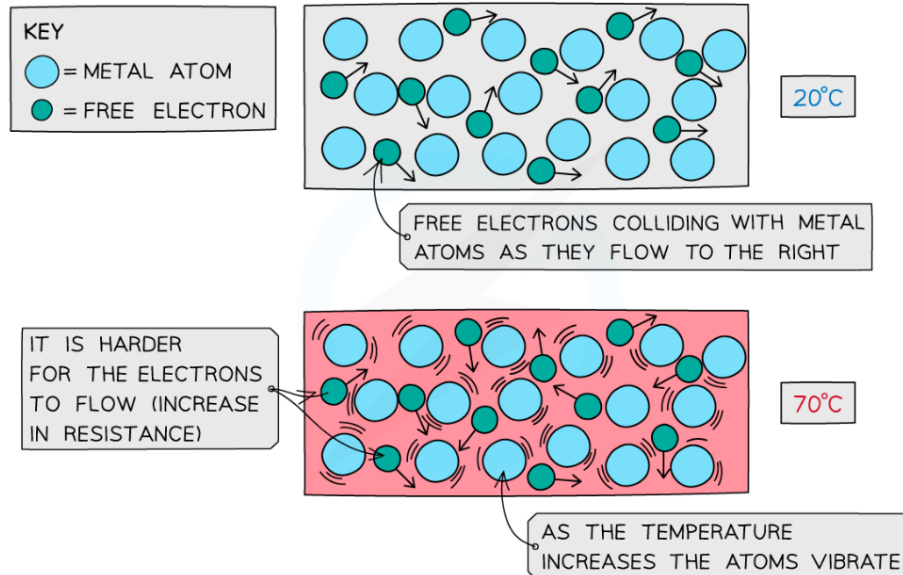
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# ***n*-Type and *p*-Type Semiconductors**

## Effects of heat:

Conductor is heated → atoms tend to vibrate  
reduces electrons movement  
current flow reduces = resistance increases  
positive temperature coefficient (PTC) of resistance



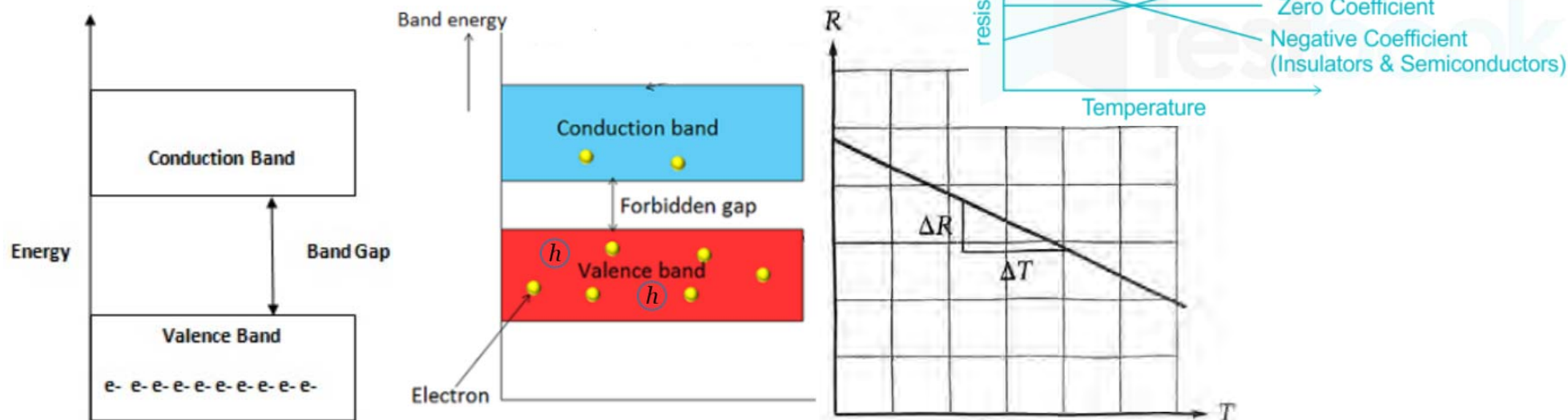
# ***n*-Type and *p*-Type Semiconductors**

## Effects of heat:

Undoped semiconductor material at absolute zero temperature ( $-273^{\circ}\text{C}$ )  $\rightarrow$   
no electrons in conduction band + no holes in valence band = insulator

Semiconductor is heated  $\rightarrow$

electrons in conduction band + holes in valence band + thermal vibration of atoms  
few electrons to be impeded +  $e$ - $h$  pairs generation dominates =  
current flow increases = resistance decreases  
negative temperature coefficient (NTC) of resistance



# ***pn-Junction***

Junction of *p*-type and *n*-type:

*p*-type → holes are uniformly distributed

*n*-type → electrons are uniformly distributed

*pn*-junction →

electrons and holes diffuse across junction

free electrons fill adjacent holes on *p*-side →

create negative ions

electrons leave positive ions on *n*-side

close to junction →

positive ions create positive voltage on *n*-side

negative ions create negative voltage on *p*-side

negative voltage repels electrons crossing from *n*-side

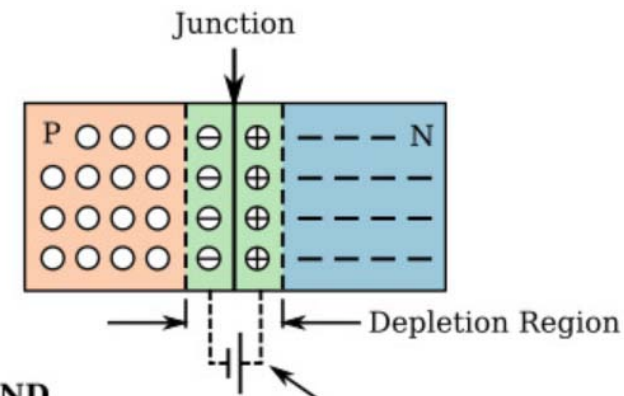
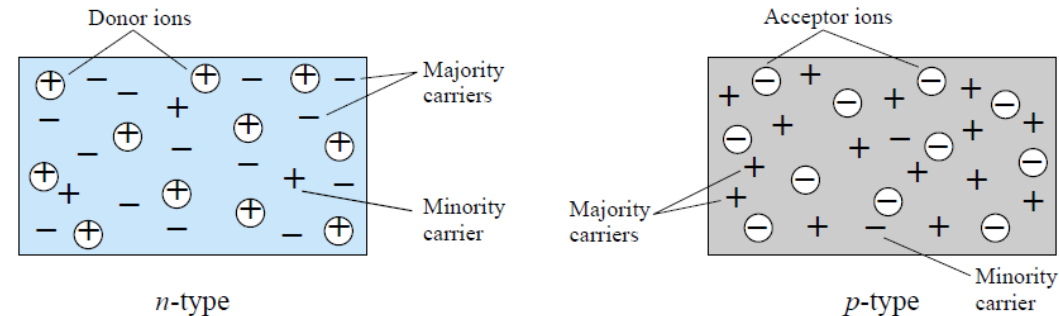
positive voltage repels holes movement from *n*-side

creates barrier voltage

Ge = 0.3 V, Si = 0.7 V

barrier voltage → opposes flow of majority carriers

assists flow of minority carriers



## LEGEND

- Hole
- Free Electron
- ⊖ Negative Ion
- ⊕ Positive Ion

# ***pn-Junction***

## Depletion region:

*n*-side → donor impurity atoms

lost free electrons = becomes positively charged ions

*p*-side → acceptor impurity atoms

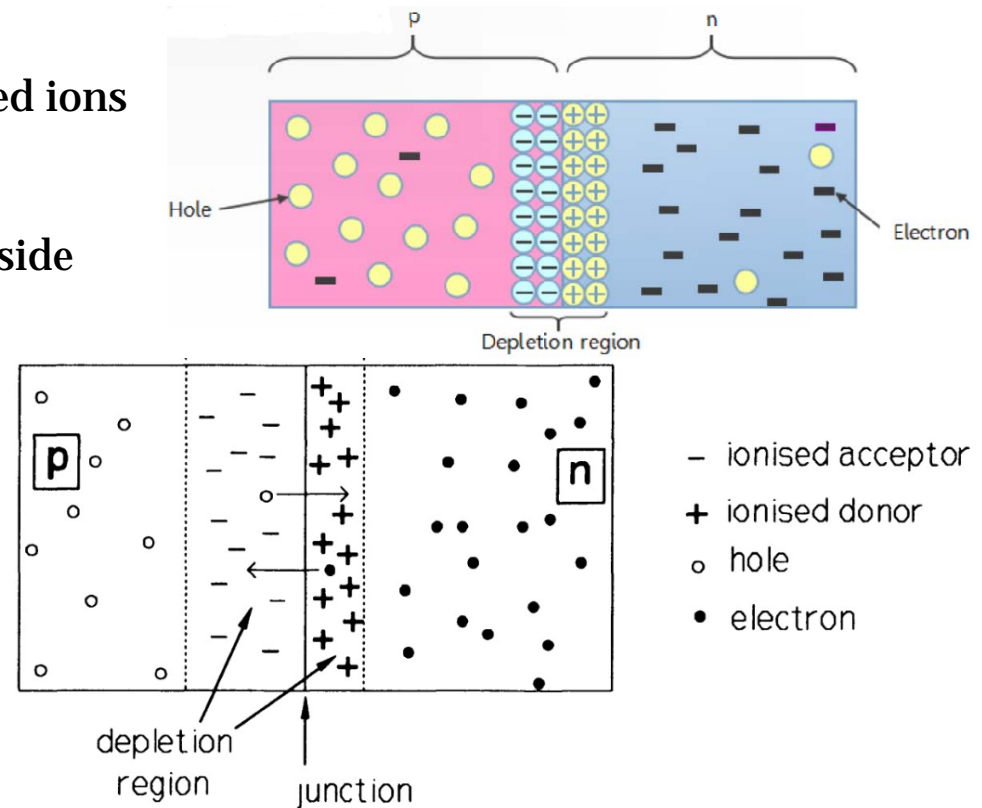
lost holes = becomes negatively charged ions

Equal number of impurity atoms involved

Equal doping densities → equal widths on each side

Unequal doping densities →

depletion region penetrates deeper  
into lightly doped side



# Biased Junction

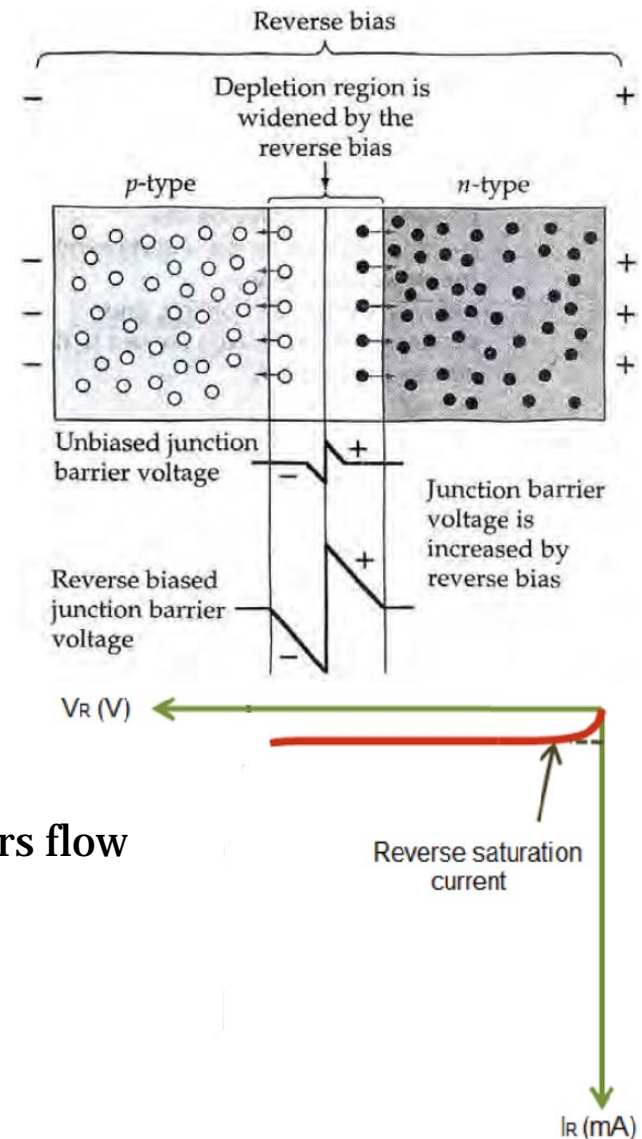
## Reverse-biased junction:

External reverse bias voltage = positive to  $n$ -side  
negative to  $p$ -side

Holes on  $p$ -side are attracted away from junction  
Electrons on  $n$ -side are attracted away from junction  
= Depletion region widens + Barrier voltage increases

Majority charge carrier current flow stops  
Minority carriers on each side can cross junction =  
Very small reverse current flows  
Nanoamps to microamps current flows

Very small reverse bias voltage is necessary for all minority carriers flow  
Equivalent current = Reverse saturation current



# Biased Junction

## Forward-biased junction:

External forward bias voltage = positive to  $p$ -side  
negative to  $n$ -side

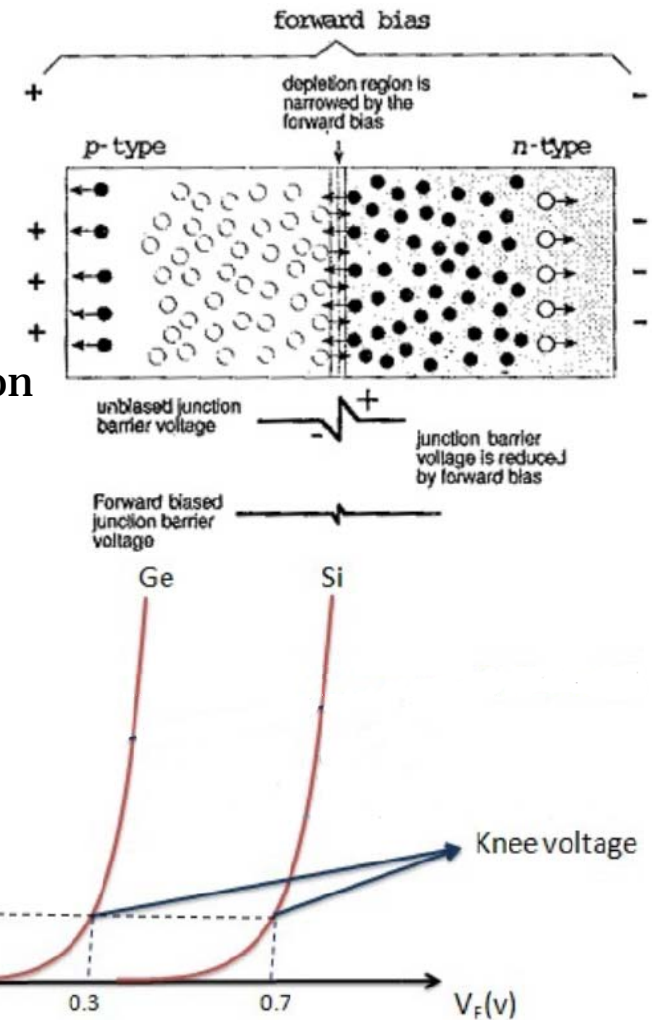
Holes on  $p$ -side are repelled from +ve terminal toward junction  
Electrons on  $n$ -side are repelled from -ve terminal toward junction  
= Depletion region reduced + Barrier voltage decreases

High applied bias voltage →  
barrier voltage disappears  
 $e$  from  $n$ -side attracted to +ve bias terminal  
 $h$  from  $p$ -side attracted to -ve bias terminal  
majority charge carrier current flows easily

Very little forward current flows until

$V_F > \text{junction barrier voltage}$

Above knee voltage,  $I_F$  increases linearly with increase in  $V_F$



# Junction Current and Voltage

Shockley equation:

Relating *pn*-junction current and voltage levels.

Also known as diode equation.

$$I_D = I_0 [e^{V_D/nV_T} - 1] \quad (1.1)$$

$I_D$  = junction current

$I_0$  = reverse saturation current

$V_D$  = junction voltage

$n = 1$  for Ge,  $2$  for Si

$V_T = kT/q$  = thermal voltage (1.2)

$k$  = Boltzmann's constant =  $1.38 \times 10^{-23}$  J/K [ $\text{m}^2\text{kgs}^{-2}\text{K}^{-1}$ ]

$T$  = absolute temperature

$q$  = electric charge =  $1.6 \times 10^{-19}$  C

Junction voltage for a given forward current  $\rightarrow$

$$V_D = (nV_T) \ln(I_D/I_0) \quad (1.3) \quad [\text{assumption: } I_D \gg I_0]$$



# Junction Current and Voltage

## Problem-1:

A silicon *pn*-junction has a reverse saturation current  $I_0 = 30$  nA at a temperature of 300 K. Calculate the junction current when the applied voltage is (a) 0.7 V forward bias, (b) 10 V reverse bias. Assume  $V_T = 26$  mV at  $T = 300$  K.

(a) 0.7 V forward bias

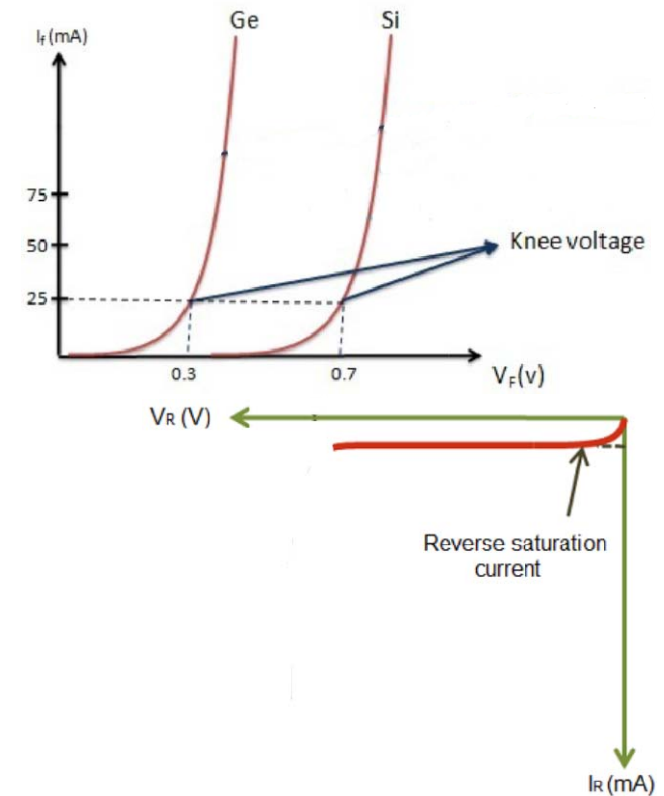
$$V_D/nV_T = 0.7/(2 \times 26 \times 10^{-3}) = 13.46$$

$$I_D = I_0 [e^{V_D/nV_T} - 1] = 30 \times 10^{-9} [e^{13.46} - 1] = 21 \text{ mA}$$

(b) 10 V reverse bias

$$V_D/nV_T = -10/(2 \times 26 \times 10^{-3}) = -192$$

$$I_D = I_0 [e^{V_D/nV_T} - 1] = 30 \times 10^{-9} [e^{-192} - 1] = -30 \text{ nA}$$



# Junction Current and Voltage

## Problem-2:

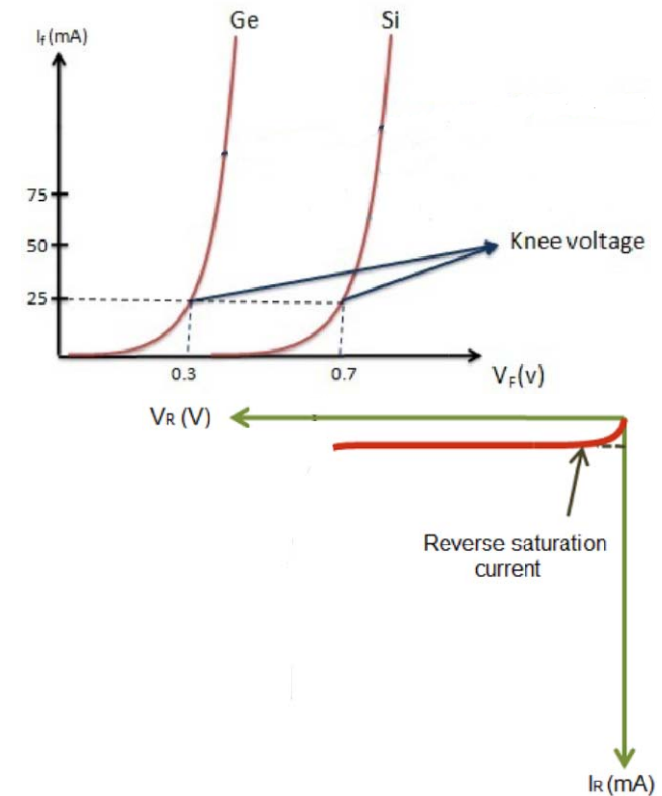
A silicon *pn*-junction has a reverse saturation current  $I_0 = 30$  nA at a temperature of 300 K. Calculate the junction forward bias voltage required to produce a current of (a) 0.1 mA, (b) 10 mA. Assume  $V_T = 26$  mV at  $T = 300$  K.

(a)  $I_D = 0.1$  mA

$$\begin{aligned} V_D &= (nV_T)\ln(I_D/I_0) \\ &= 2 \times 26 \times 10^{-3} \times \ln(0.1 \times 10^{-3} / 30 \times 10^{-9}) \\ &= 422 \text{ mV} \end{aligned}$$

(b)  $I_D = 10$  mA

$$\begin{aligned} V_D &= (nV_T)\ln(I_D/I_0) \\ &= 2 \times 26 \times 10^{-3} \times \ln(10 \times 10^{-3} / 30 \times 10^{-9}) \\ &= 661 \text{ mV} \end{aligned}$$



# ***pn-Junction Diode***

Diode →

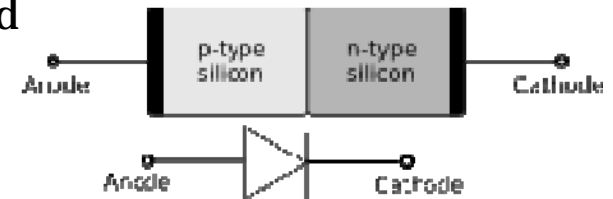
*pn*-junction + connecting leads

one-way device = low resistance when forward biased

open switch when reverse biased

constant forward voltage drop

constant reverse saturation current



Diode is destroyed if →

high forward current overheats device

large reverse voltage causes junction to break down =  
reverse breakdown

Typical forward and reverse characteristics of diode →

